

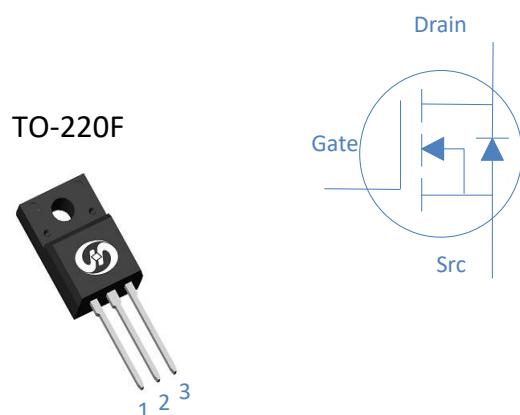
**100V N-Ch Power MOSFET**
**Feature**

- ◊ High Speed Power Switching, Logic Level
- ◊ Enhanced Body diode dv/dt capability
- ◊ Enhanced Avalanche Ruggedness
- ◊ 100% UIS Tested, 100% Rg Tested
- ◊ Lead Free, Halogen Free

$V_{DS}$	100	V
$R_{DS(on),typ}$	$V_{GS}=10V$	7.1 mΩ
$R_{DS(on),typ}$	$V_{GS}=4.5V$	9.3 mΩ
$I_D$ (Silicon Limited)	45	A

**Application**

- ◊ Synchronous Rectification in SMPS
- ◊ Hard Switching and High Speed Circuit
- ◊ DC/DC in Telecoms and Industrial



Part Number	Package	Marking
HGA080N10AL	TO-220F	GA080N10AL

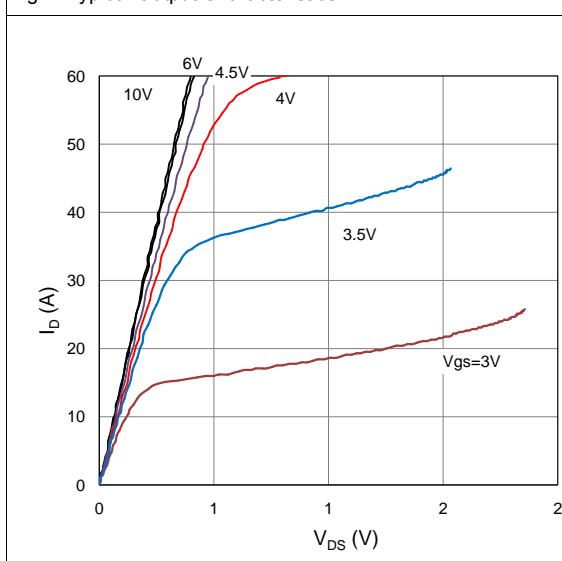
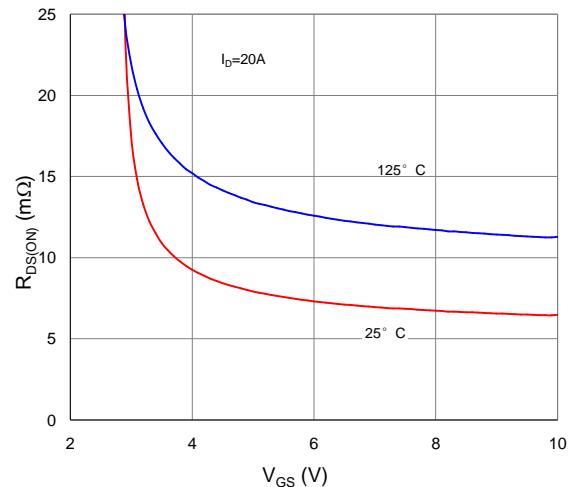
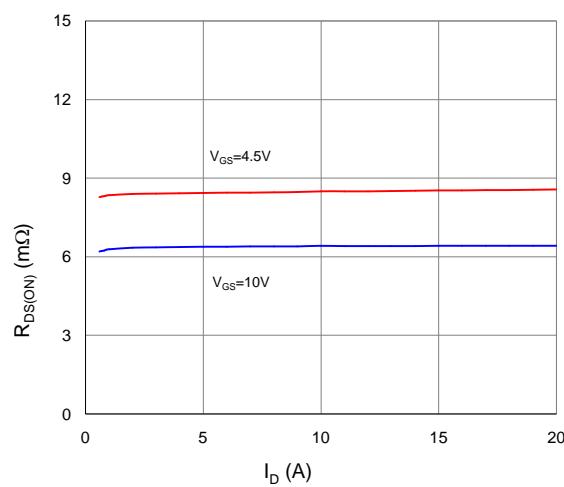
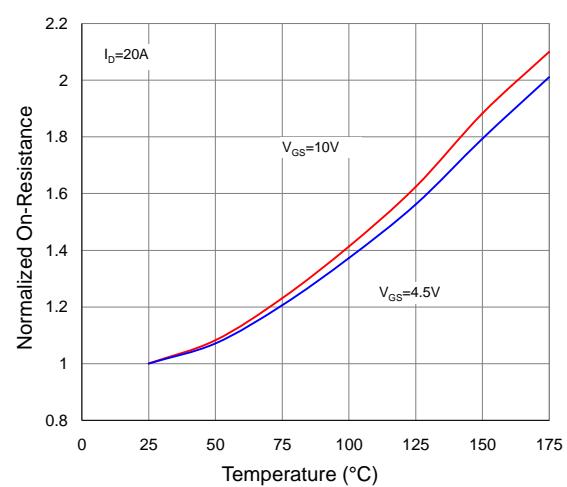
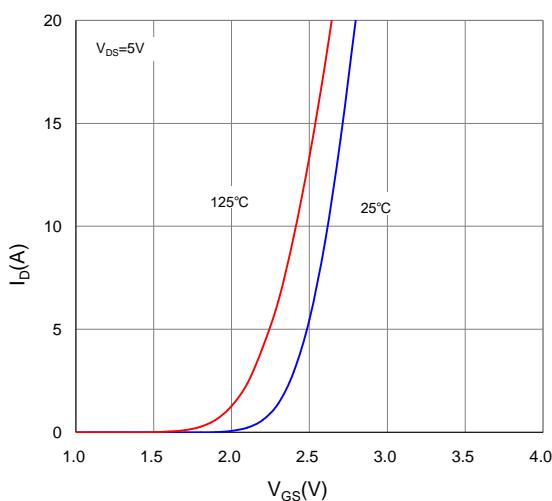
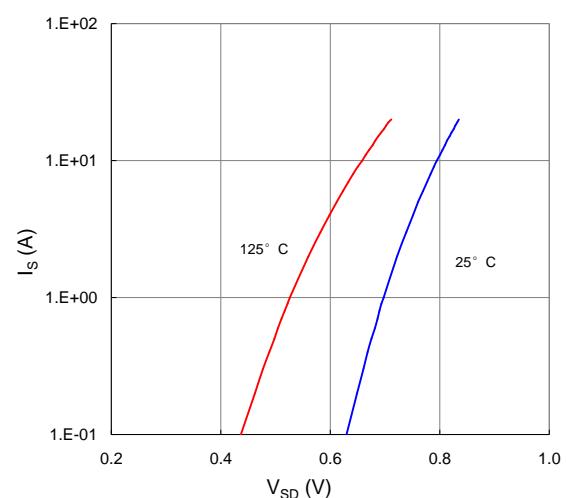
**Absolute Maximum Ratings at  $T_j=25^\circ C$  (unless otherwise specified)**

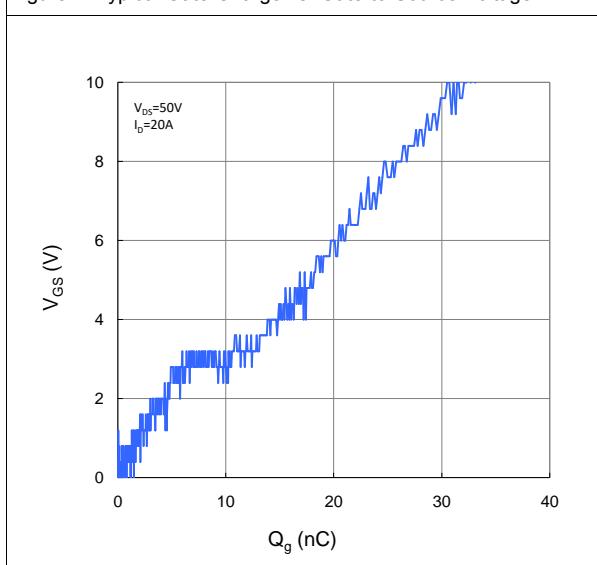
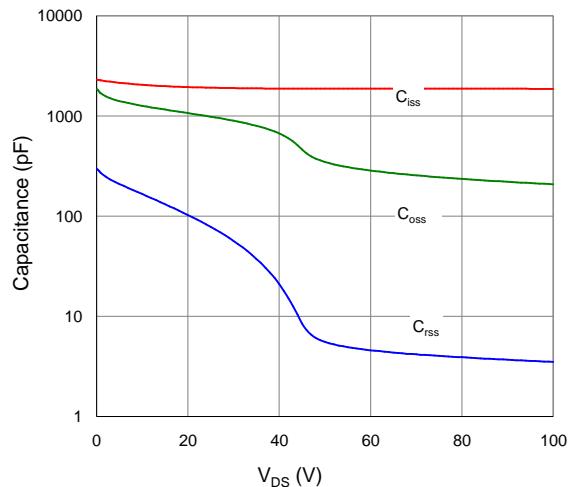
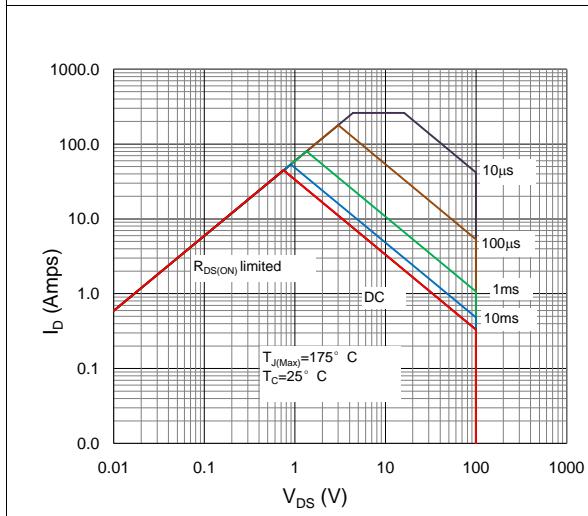
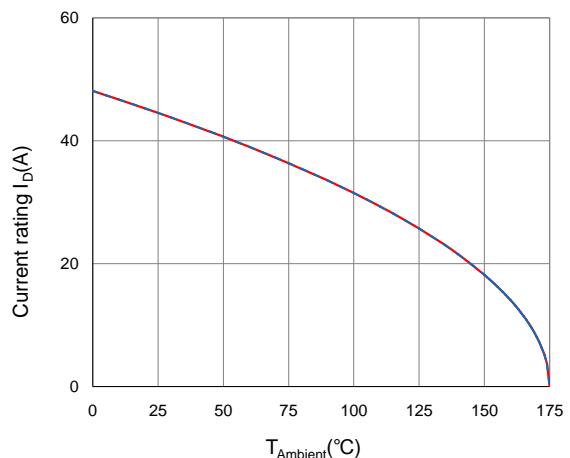
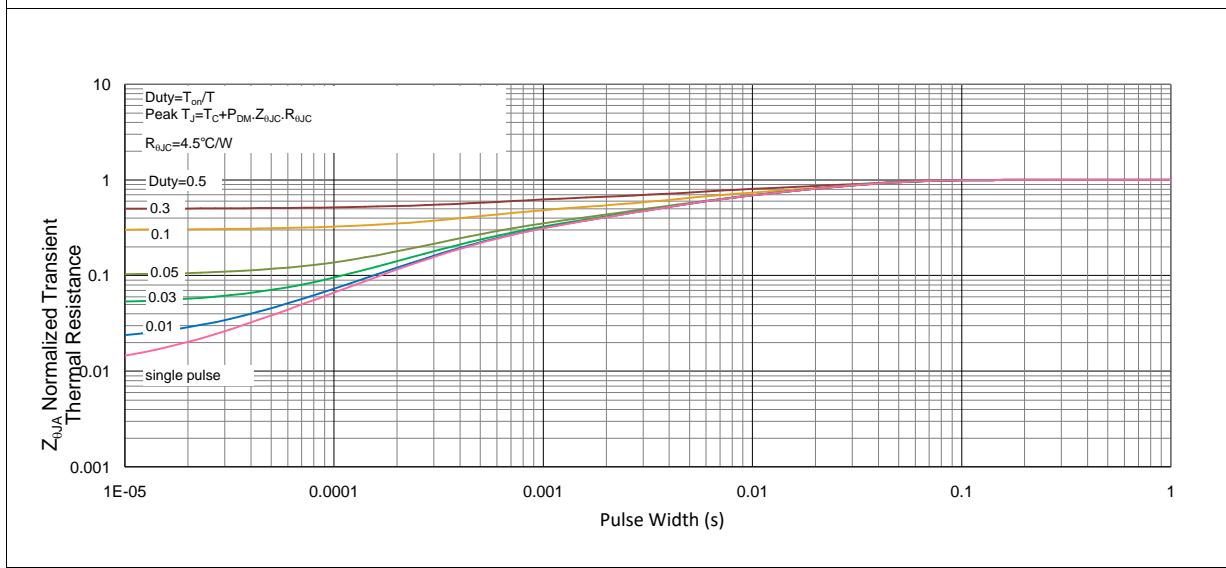
Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	$I_D$	$T_C=25^\circ C$	45	A
		$T_C=100^\circ C$	31	
Drain to Source Voltage	$V_{DS}$	-	100	V
Gate to Source Voltage	$V_{GS}$	-	$\pm 20$	V
Pulsed Drain Current	$I_{DM}$	-	260	A
Avalanche Energy, Single Pulse	$E_{AS}$	$L=0.4mH, T_C=25^\circ C$	245	mJ
Power Dissipation	$P_D$	$T_C=25^\circ C$	33	W
Operating and Storage Temperature	$T_J, T_{stg}$	-	-55 to 175	°C

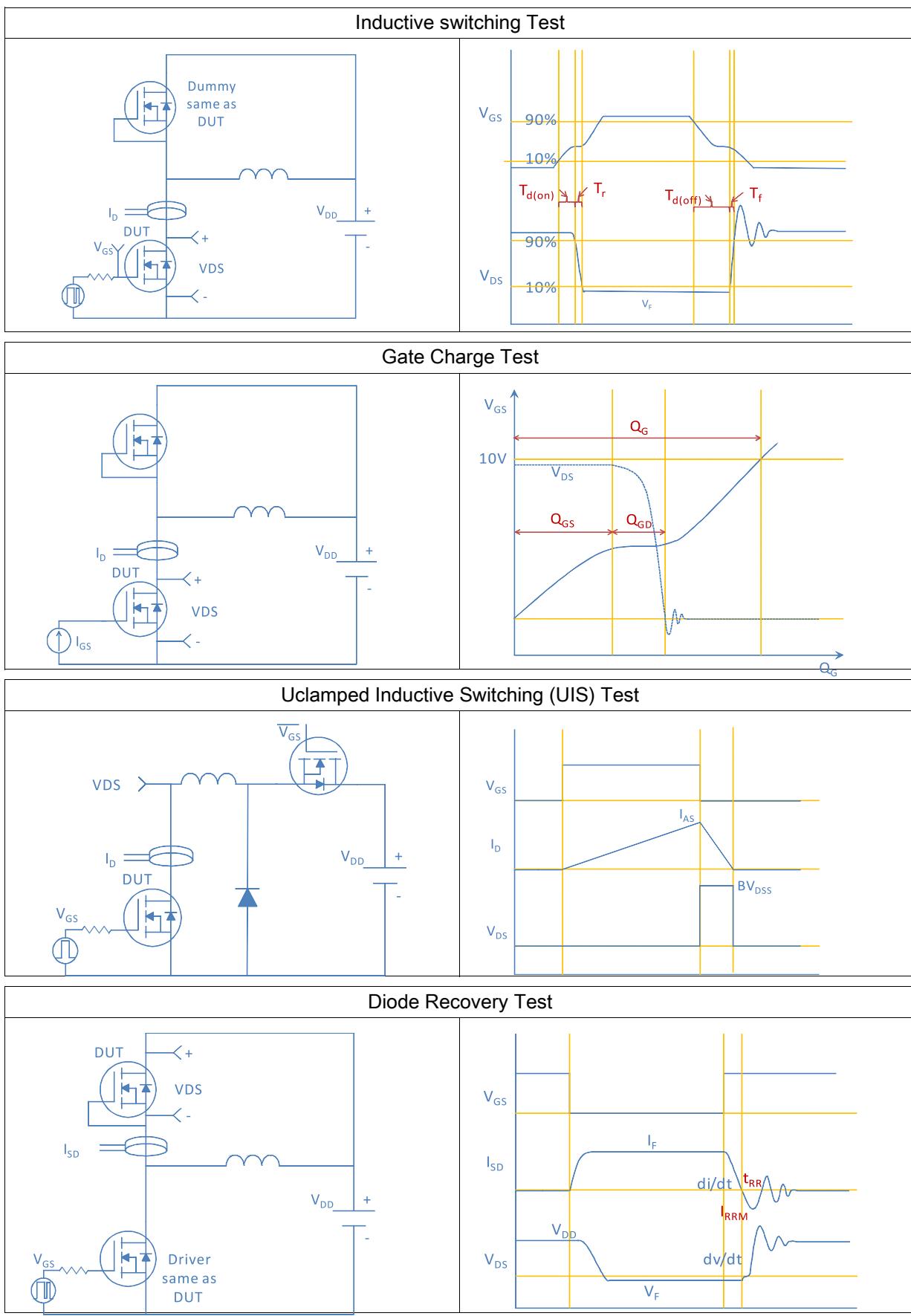
**Absolute Maximum Ratings**

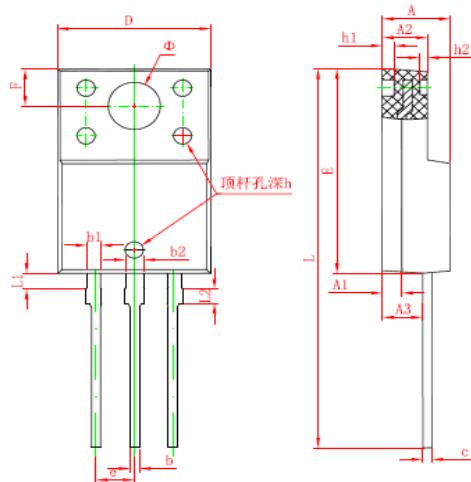
Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	60	°C/W
Thermal Resistance Junction-Case	$R_{\theta JC}$	4.5	°C/W



**Fig 1. Typical Output Characteristics**

**Figure 2. On-Resistance vs. Gate-Source Voltage**

**Figure 3. On-Resistance vs. Drain Current and Gate Voltage**

**Figure 4. Normalized On-Resistance vs. Junction Temperature**

**Figure 5. Typical Transfer Characteristics**

**Figure 6. Typical Source-Drain Diode Forward Voltage**


**Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage**

**Figure 8. Typical Capacitance vs. Drain-to-Source Voltage**

**Figure 9. Maximum Safe Operating Area**

**Figure 10. Maximum Drain Current vs. Case Temperature**

**Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient**




**Package Outline**
**TO-220F, 3 leads**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.350	4.650	0.169	0.185
A1	1.300 REF.			0.051 REF.
A2	2.850	3.150	0.112	0.124
A3	2.600	2.800	0.102	0.110
b	0.500	0.750	0.020	0.030
b1	0.800	1.050	0.031	0.041
b2	1.100	1.350	0.043	0.053
c	0.500	0.750	0.020	0.030
D	9.960	10.360	0.392	0.408
E	14.800	15.200	0.583	0.598
e	2.540 TYP.		0.100 TYP.	
F	2.700 REF.		0.106 REF.	
$\Phi$	3.500 REF.		0.138 REF.	
h	0.000	0.300	0.000	0.012
h1	0.800 REF.		0.031 REF.	
h2	0.500 REF.		0.020 REF.	
L	28.000	28.400	1.102	1.118
L1	1.100	1.300	0.043	0.051
L2	0.920	1.080	0.036	0.043